

SOT-227 Single Thyristor Power Module, 160 A, 1200 V



PRIMARY CHARACTERISTICS					
V _{RRM} / V _{DRM}	1200 V				
V _{TM} (typical) at 150 A, 25 °C	1.3 V				
I _{T(AV)} , T _C = 75 °C	158 A ⁽¹⁾				
Package	SOT-227				
Circuit	Single thyristor				

Note

FEATURES

- High voltage
- Industrial standard package
- Low thermal resistance
- UL pending
- · Designed and qualified for industrial level
- Material categorization: for definitions of compliance please see www.vishav.com/doc?99912

BENEFITS

- Excellent thermal performances
- · High surge capability
- Easy mounting on heatsink
- Thyristor for line frequency

APPLICATIONS

Line rectifying 50 Hz / 60 Hz

- Softstart AC motor control
- DC motor control
- Power converter
- AC power control
- · Lighting and temperature control

MAJOR RATINGS AND CHARACTERISTICS						
SYMBOL	CHARACTERISTICS	VALUES	UNITS			
I _{T(AV)}	75 °C	158				
1	50 Hz	1390	А			
I _{TSM}	60 Hz	1455				
l ² t	50 Hz	9.6	kA ² s			
1-1	60 Hz	8.8	KA-S			
I ² √t		96.6	kA²√s			
V _{RRM} / V _{DRM}		1200	V			
T _{Stg}		-40 to +125	°C			
T _J		-40 to +125				

ELECTRICAL SPECIFICATIONS

VOLTAGE RATINGS			
V _{RRM} , MAXIMUM REPETITIVE PEAK REVERSE VOLTAGE V	V _{RSM} , MAXIMUM NON-REPETITIVE PEAK REVERSE VOLTAGE V	V _{DRM} , MAXIMUM REPETITIVE PEAK OFF-STATE VOLTAGE, GATE OPEN CIRCUIT V	I _{RRM,} I _{DRM} AT 125 °C mA
1200	1300	1200	10

⁽¹⁾ Maximum continuous collector current admitted 100 A to do not exceed the maximum temperature of terminals



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ON-STATE CONDUCTION						
PARAMETER	SYMBOL	TEST CONDITIONS		VALUES	UNITS	
Maximum average on-state current (thyristors)	I _{T(AV)}	180° conduction, half sine wave, T _C = 75 °C		158		
		t = 10 ms	No voltage	Sinusoidal	1390	
Maximum peak, one-cycle non-repetitive	L	t = 8.3 ms	reapplied	half wave,	1455	Α
on-state	I _{TSM}	t = 10 ms	100 % V _{RRM}	initial	1169	
		t = 8.3 ms	reapplied	$T_J = T_J \text{ maximum}$	1224	
		t = 10 ms	No voltage		9.6	
Maximum I ² t for fusing	I ² t	t = 8.3 ms	reapplied	Initial	8.8	kA ² s
Maximum i-t for fusing	1-1	t = 10 ms	100 % V _{RRM}	$T_J = T_J \text{ maximum}$	6.8	
	t = 8.3 ms reapplied		6.2			
Maximum l²√t for fusing	I ² √t (1)	t = 0.1 ms to 10 ms, no voltage reapplied		96.6	kA²√s	
Waximum Veror lasing	1-11(1)	$T_J = T_J$ maximum				
Maximum value or threshold voltage	V _{T(TO)} (2)	Low level (3)	$T_J = T_J$ maximum		0.82	V
Waximum value of uneshold voltage	V I(IO) (/	High level ⁽⁴⁾			0.86	
Maximum value of on-state slope resistance	r _t (2)	Low level (3)	$T_{.1} = T_{.1}$ maximum		3.95	mΩ
Waximum value of on state slope resistance	'τ''	High level ⁽⁴⁾	ij – ij maxim	3111	3.91	11122
Maximum peak on-state voltage	V _{TM}	I _{TM} = 150 A	T _J = 25 °C		1.45	V
waximum peak on state voltage	VIM	$T_{\rm J} = 150 {\rm ^{\circ}C}$			1.41	V
Maximum non-repetitive rate of rise of turned	dl/dt	$T_J = 25 ^{\circ}\text{C}$, from 0.67 V_{DRM} , $I_{TM} = \pi \times I_{T(AV)}$, $I_g = 500 \text{mA}$,		150	A/µs	
on current	a, at	$t_r < 0.5 \ \mu s, \ t_p > 6 \ \mu s$, v µo		
Maximum holding current	I _H	T _J = 25 °C, anode supply = 6 V, resistive load, gate open circuit		250	mA	
Maximum latching current	IL	T _J = 25 °C, anode supply = 6 V, resistive load 400				

Notes

- (1) I^2t for time $t_x = I^2\sqrt{t} \ x \ \sqrt{t_x}$
- $^{(2)}$ Average power = $V_{T(TO)} \; x \; I_{T(AV)} + r_t \; x \; (I_{T(RMS)})^2$
- (3) 16.7 % $\times \pi \times I_{AV} < I < \pi \times I_{AV}$
- $^{(4)}~I>\pi~x~I_{AV}$

TRIGGERING					
PARAMETER	SYMBOL	TEST CO	ONDITIONS	VALUES	UNITS
Maximum peak gate power	P _{GM}			12	W
Maximum average gate power	P _{G(AV)}			3	VV
Maximum peak gate current	I _{GM}			3	Α
Maximum peak negative gate voltage	-V _{GM}			10	
Maximum gate voltage required to trigger		T _J = -40 °C	Anode supply = 6 V resistive load	4.0	V
	V_{GT}	T _J = 25 °C		2.1	
		T _J = 125 °C		1.7	
		T _J = -40 °C	Anode supply = 6 V resistive load	270	
Maximum gate current required to trigger	I _{GT}	T _J = 25 °C		150	mA
		T _J = 125 °C		80	
Maximum gate voltage that will not trigger	V_{GD}	T _J = 150 °C, 80 % V _{DRM} applied		0.2	V
Maximum gate current that will not trigger	I _{GD}	T _J = 150 °C, 80 % V _{DRM} applied		10	mA

BLOCKING				
PARAMETER	SYMBOL	TEST CONDITIONS	VALUES	UNITS
Maximum peak reverse and off-state leakage current at V _{RRM} , V _{DRM}	I _{RRM,} I _{DRM}	T _J = 125 °C, gate open circuit	10	mA
Maximum RMS insulation voltage	V _{INS}	50 Hz	2500 (1 min)	V
Maximum critical rate of rise of off-state voltage	dV/dt	T _J = 150 °C, linear to 0.8 V _{DRM}	1000	V/µs



THERMAL AND MECHANICAL SPECIFICATIONS					
PARAMETER		SYMBOL	TEST CONDITIONS	VALUES	UNITS
Junction operating temperature	range	TJ		-40 to +125	°C
Storage temperature range		T _{Stg}		-40 10 +125	C
Maximum internal thermal resis junction to case per leg	tance,	R _{thJC}	DC operation	0.2	°C/W
Typical thermal resistance, case to heat sink per module		R _{thCS}	Mounting surface flat, smooth, and greased	0.1	C/VV
Mounting torque ± 10 %	to heat sink	-	A mounting compound is recommended and the torque should be rechecked after a period of 3 hours to allow for the spread of the compound.	1.3	Nm
Approximate weight				30	g
Case style				SOT	-227

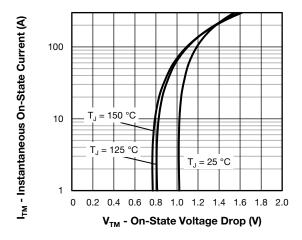


Fig. 1 - I_{TM} vs. V_{TM} (On-State Voltage Drop Characteristics)

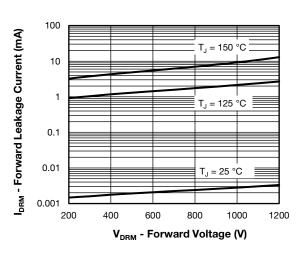


Fig. 2 - I_{DRM} vs. V_{DRM} (Forward Leakage Current)

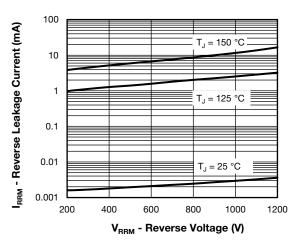


Fig. 3 - I_{RRM} vs. V_{RRM} (Reverse Leakage Current)

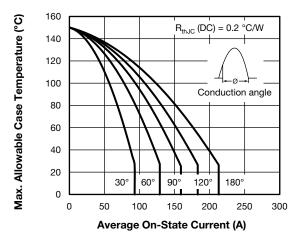


Fig. 4 - Maximum Allowable Case Temperature vs. Average On-State Current (Current Rating Characteristics)



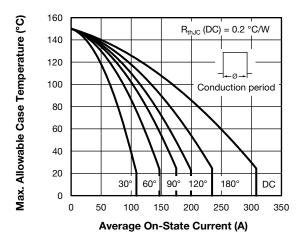


Fig. 5 - Maximum Allowable Case Temperature vs. Average On-State Current (Current Rating Characteristics)

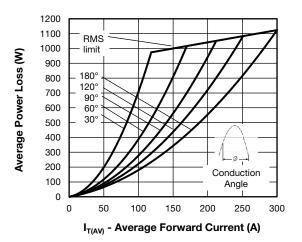
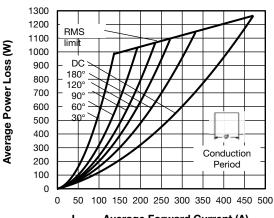
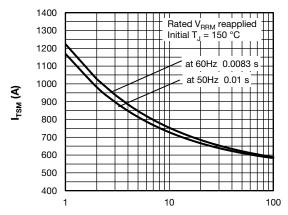


Fig. 6 - Average Power Loss vs. Average Forward Current (Forward Power Loss Characteristics)



I_{T(AV)} - Average Forward Current (A)

Fig. 7 - Average Power Loss vs. Average Forward Current (Forward Power Loss Characteristics)



Number of Equal Amplitude Half Cycle Current Pulses (N)

 ${\rm Fig.~8 - I_{TSM}~vs.~N} \\ {\rm (Non-Repetitive~peak~Forward~Surge~Current~vs.~Number~Pulses)}$

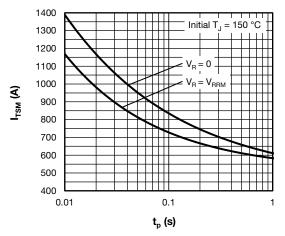


Fig. 9 - I_{TSM} vs. t_p (Non-Repetitive peak Forward Surge Current vs. Pulse Duration)



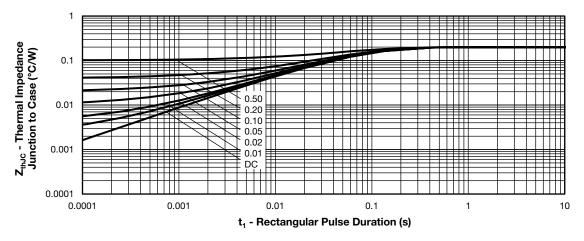
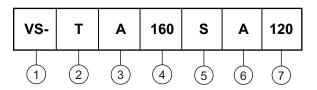


Fig. 10 - Z_{thJC} Thermal Impedance Junction to Case vs. t₁ Rectangular Pulse Duration (Maximum Thermal Impedance Z_{thJC} Characteristics)

ORDERING INFORMATION TABLE

Device code



1 - Vishay Semiconductors product

2 - Thyristor dice

Present silicon generation

4 - Rating current

5 - Single thyristor

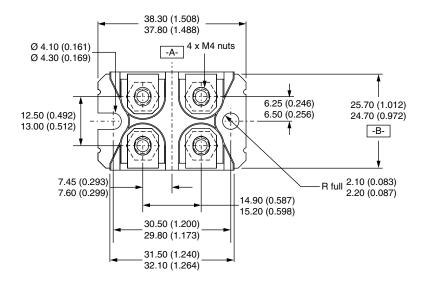
6 - Isolated SOT-227

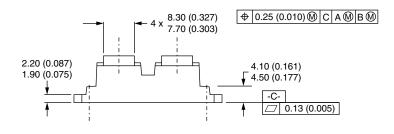
7 - Voltage rating 120 = 1200 V

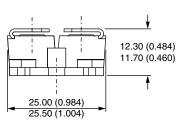
CIRCUIT DESCRIPTION	CIRCUIT CONFIGURATION CODE	CIRCUIT DRAWING	
Single thyristor	S	Lead Assignment 4 2 1	3

LINKS TO RELATED DOCUMENTS				
Dimensions	www.vishay.com/doc?95423			
Packaging information	www.vishay.com/doc?95425			
Application note	www.vishay.com/doc?95527			

DIMENSIONS in millimeters (inches): **SOT-227 Gen 2**





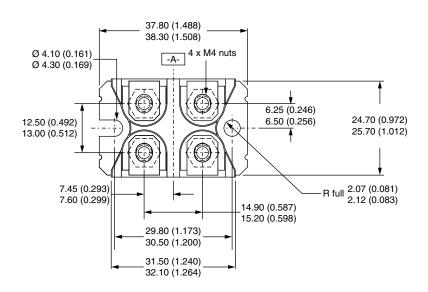


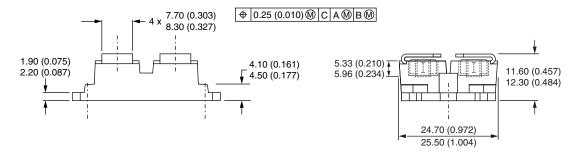
Note

Controlling dimension: millimeter

SOT-227 Generation 2

DIMENSIONS in millimeters (inches)





Note

· Controlling dimension: millimeter



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